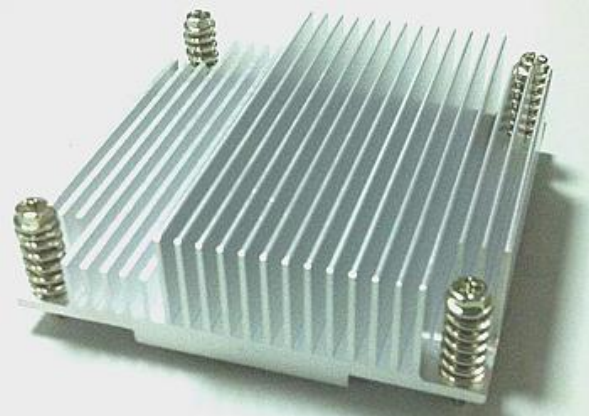
DEL-00055-N1-GP



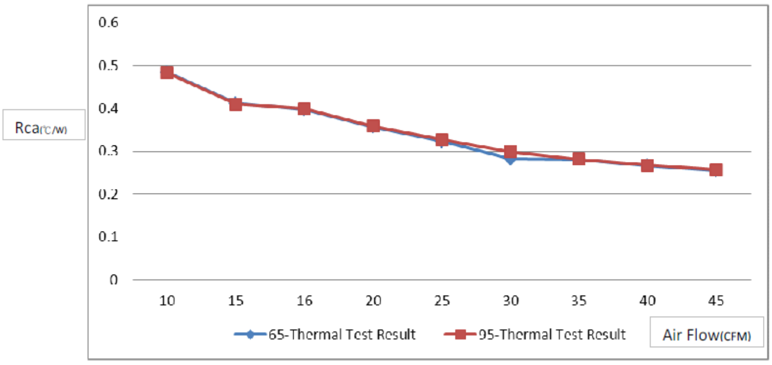
Thermal and Mechanical Spec

Thermal performance for 95W~150W CPU

HSK Assembly Weight: 250 g

CPU Loading: 65 lbf

Performance Curve



Application

LGA 2011 (Socket R Square) M4

Test result:

	65W	95W
Flow (CFM)	Rca (℃/W)	Rca (℃/W)
10	0.4845	0.4833
15	0.4118	0.4103
16	0.3975	0.3992
20	0.3571	0.3591
25	0.3236	0.3267
30	0.2816	0.299
35	0.281	0.281
40	0.2668	0.2673
45	0.2552	0.2566

Component Specifications

Application System	1U+ Form Factor Passive Solution
Material	Aluminum Extrusion
Dimension	90L x 90W x 27H mm
Fin	Thick= 1.16mm , Pitch= 2.69mm , 24 fin
Thermal interface Material	ShinEtsu 7762 (Ø24mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

Safety